

	! " #	\$! % & '	! () % * +	, -	. /
A	2018-10-19		0 1 - 2	3 4 5	
B	2021-6-7	4/7	6 7 8 9 : ; < b 8 9 = > ? @ A B C D : = > ? E F G H 5 I 50000 J K L M N 7 I 70000 J O 89)X89)X9)、8;)X8;)X28) M N 88<X88<X9)、88)X88;X8<<	P Q	R 4 S
				-	

/ Descriptions

T U V F W A X Y Z O [\] ^ _ 2000V O ` \] A _ 1.0A O S M A a F b
Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage _ 2)) V, Forward
Current: *.) A , SMA package.

/ Features

c d e f g h O i j k l m n RoHS o p 2011/65/EU O q r T U V F b i s t u b
Glass Passivated Chip Junction, Lead free in comply with EU RoQS 2) **/<;/EU directives, For
surface mounted applications. QF product.

/ Applications

v w r x .
General purpose.

/ Equivalent Circuit



/ Pinning



The recommended mounting pad size is



/ Marking

y z { | } b See Marking Rnstructions.

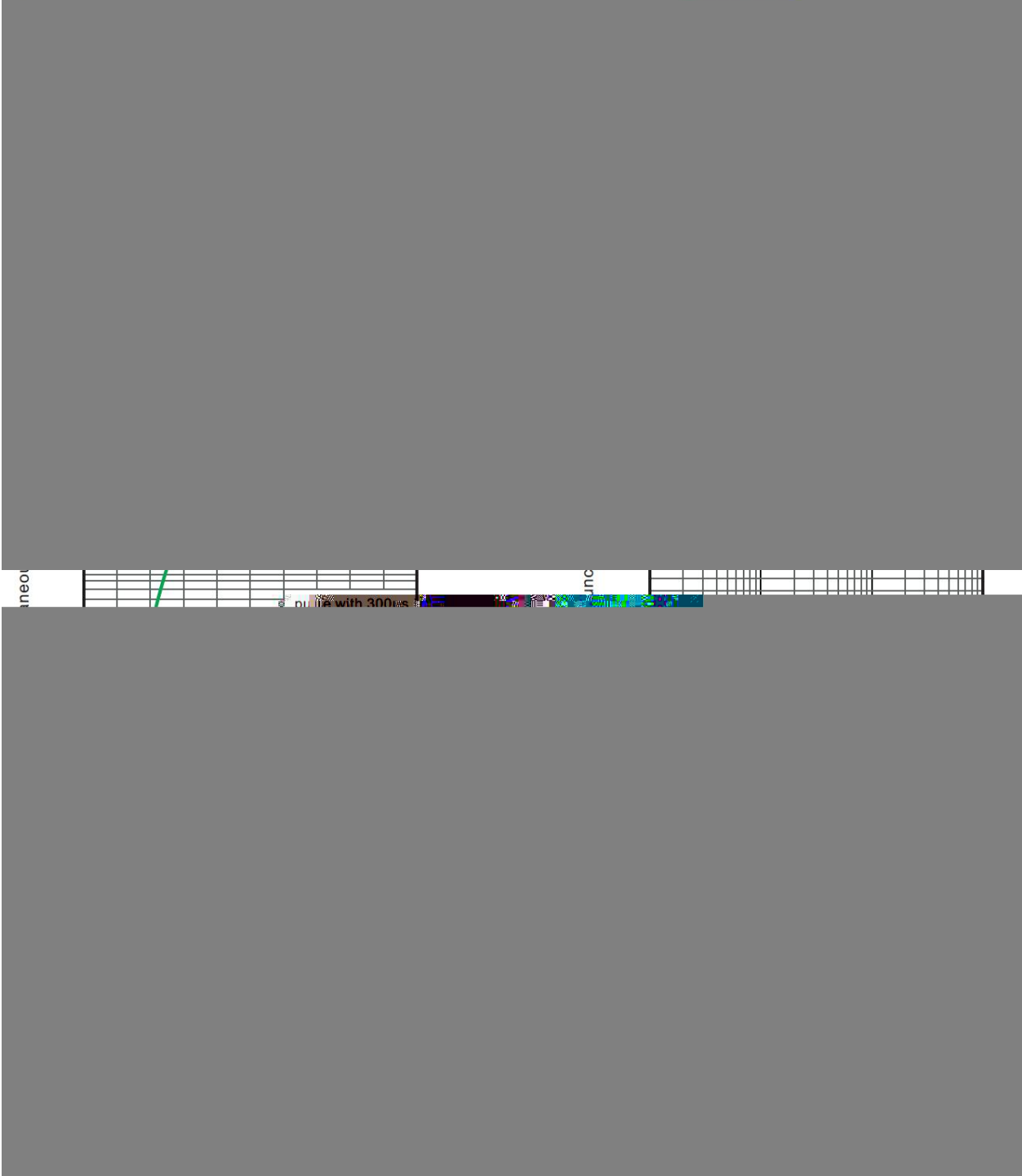
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	2)))	V
Maximum Average Forward Rectified Current at $T_C = *$) °C	$I_{F(AV)}$	*	
Peak Forward Surge Current 8.8 ms Single Qalf Sine Wave Superimposed on Rated Load(JEDEC Method)	I_{FSM}	8	

/ Electrical Characteristic Curve

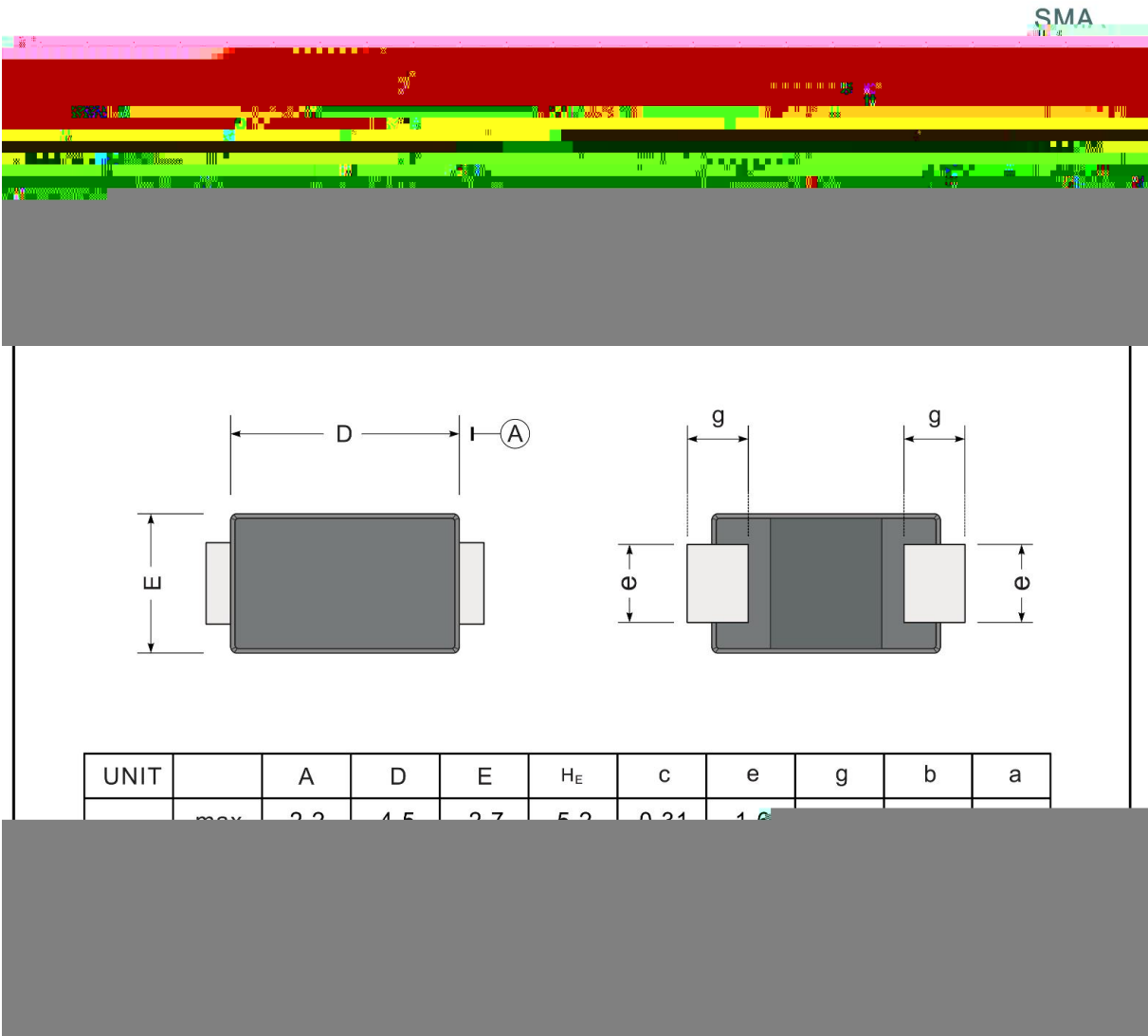
Fig.1 Forward Current Derating Curve



Fig.2 Typical Reverse Characteristics



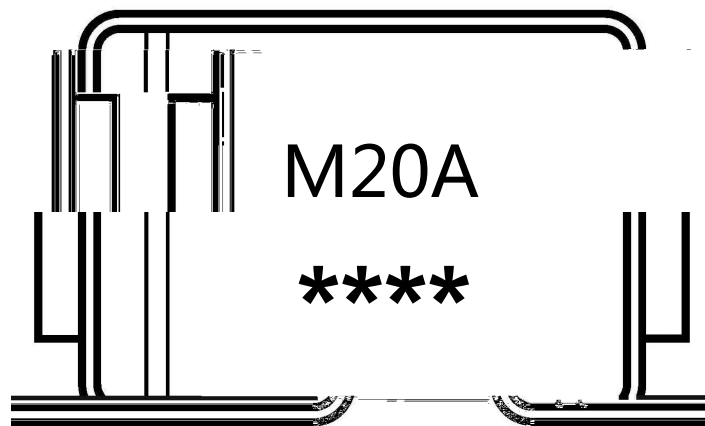
/ Package Dimensions



/ Marking Instructions



/ Marking Instructions



M20A

1 *

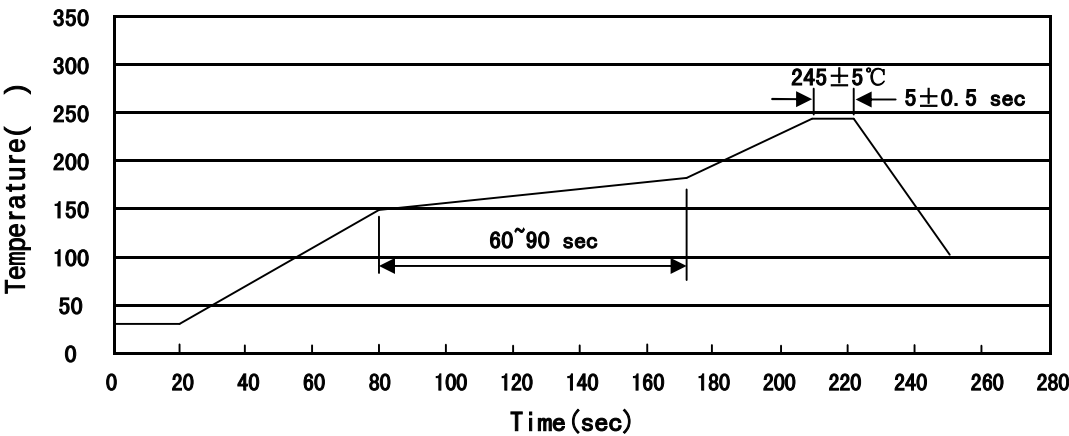
3 *

Note:

M20A Product Type Code

***** Lot No. Code The *st * means:YM Code The last 8 * means:little Lot No Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- * ;) *8) <) 9)sec; *.Preheating:* ;)~*8)°C, Time:<)~9)sec.
- 2 29; ±; ; ±).; sec; 2.Peak Temp.:29; ±; °C, Duration:; ±).; sec.
- 8 2 *)°C/sec. 8. Cooling Speed: 2~*)°C/sec.

/ Resistance to Soldering Heat Test Conditions

2<)±; °C *)±* sec. Temp.:2<)±; °C Time:*)±* sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ⁸)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
SMA	;)))	2	*))))	7	7))))	*8" ×*2	88<X88<X9)	88)X88; X8<<

/ Notices